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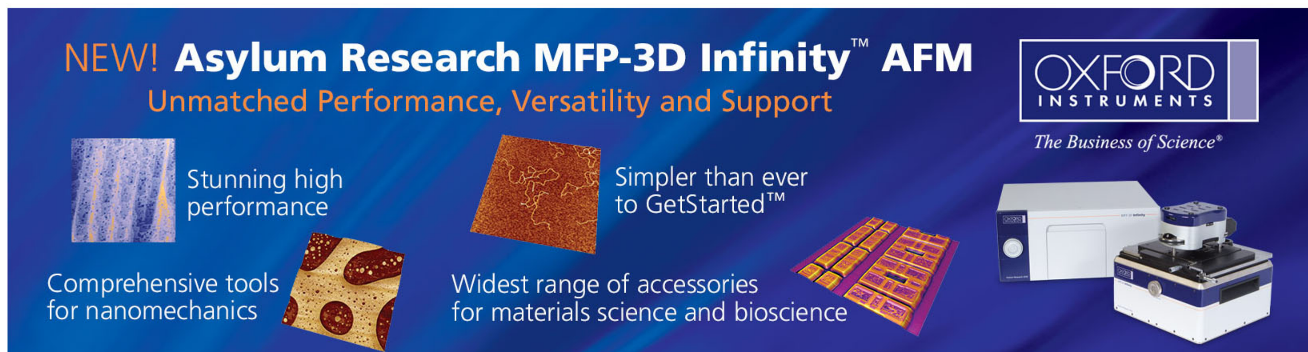

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Erratum: "Thermomigration in flip-chip SnPb solder joints under alternate current stressing" [Appl. Phys. Lett. 90, 152105 (2007)]

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The applied current densities were wrongly calculated. The revised Fig. 3 with correct current densities is shown below. In addition, the value of "9.2×10^4 A/cm^2" in the abstract, on p. 152105, and in figure caption of Fig. 2(b) should be modified as "9.7×10^3 A/cm^2." The value of "5×10^4 A/cm^2" on p. 152105 should be revised as "5.3×10^3 A/cm^2." These corrections do not affect any other part of the article and the conclusions.

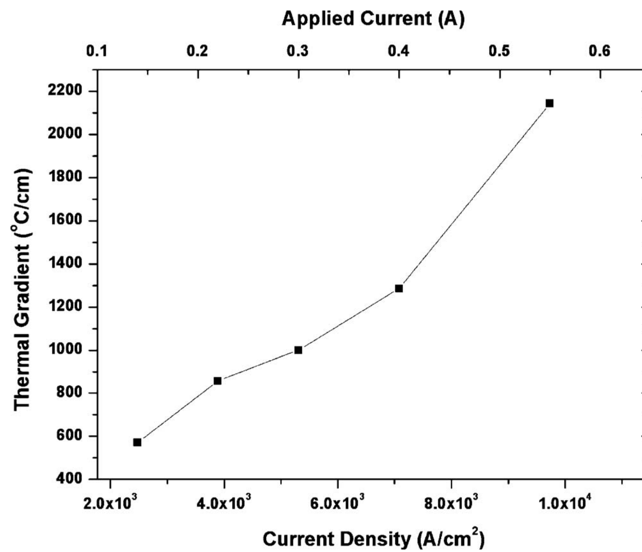

FIG. 3. The measured temperature increases in the bump as a function of applied current and current densities.

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